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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

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In re application of: My Nguyen

Attorney Docket No.: ALTRP084C1

Application No.: Not yet assigned

Examiner: Not yet assigned

Filed: February 9, 2004

Group: Not yet assigned

Title: INTERFACIAL STRENGTHENING FOR  
ELECTROLESS NICKEL IMMERSION GOLD  
SUBSTRATES

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**INFORMATION DISCLOSURE STATEMENT  
37 CFR §§1.56 AND 1.97(b)**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

The references listed in the attached PTO Form 1449, copies of which are attached, may be material to examination of the above-identified patent application. Applicants submit these references in compliance with their duty of disclosure pursuant to 37 CFR §§1.56 and 1.97. The Examiner is requested to make these references of official record in this application.

This Information Disclosure Statement is not to be construed as a representation that a search has been made, that additional information material to the examination of this application does not exist, or that these references indeed constitute prior art.

This Information Disclosure Statement is: (i) filed within three (3) months of the filing date of the above-referenced application, (ii) believed to be filed before the mailing date of a first Office Action on the merits, or (iii) believed to be filed before the mailing of a first Office Action after the filing of a Request for Continued Examination under §1.114. Accordingly, it is believed that no fees are due in connection with the filing of this Information Disclosure Statement. However, if it is determined that any fees are due, the Commissioner is hereby authorized to charge such fees to Deposit Account 500388 (Order No. ALTRP084C1).

Respectfully submitted,  
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<b>Form 1449 (Modified)</b>  <b>Information Disclosure Statement By Applicant</b>  (Use Several Sheets if Necessary)	Atty Docket No. ALTRP084C1	Application No.: Not yet assigned
	Applicant: My Nguyen Filing Date February 9, 2004	Group Not yet assigned

#### U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
	A1	6,307,160	10.2001	Mei et al.			
	A2	6,286,206	09.2001	Li, Chou H.			
	A3	6,445,069	09.2002	Ling et al.			
	A4	2002/015727	10.2002	Yamamoto, Hidetoshi			

#### Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
							Yes	No

#### Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
	C1	Goyal, et al, "Failure Mechanism of Brittle Solder Joint Fracture in the Presence of Electroless Nickel Immersion Gold (ENIG) Interface", Proceedings of the 52 <sup>nd</sup> Electronic Component and Technology Conference, 732-739, May 2002.
	C2	Binary Alloy Phase Diagrams Binary Alloy Phase Diagrams, 2 <sup>nd</sup> ed, December 1990, T.B.B. Massalski (Editor), L. Kacprzak (Editor), H. Okamoto (Editor), P.R. Subramanian (Editor), pgs 2269, 2642, 2644, 2294, 2996, 1449, 1451, 1746-1748.
Examiner		Date Considered

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.